

LINEAR TECHNOLOGY MATERIALS DECLARATION

(Engineering Calculation)

SC70

(printed on: 2014-01-20 01:13:58)

TOTAL MASS (g): 0.01042

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000464	1000000	44529.2421875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.003442	975000	330322.5		
		Iron (Fe)	7439-89-6	0.000085	24000	8157.29589844		
		Phosphorus (P)	7723-14-0	0.000001	300	95.9681930542		
		Zinc (Zn)	7440-66-6	0.000002	700	191.936386108		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-96-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		<b>Lead Frame Total:</b>				<b>0.003530</b>	<b>1000000</b>	<b>338767.71875</b>
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
Exter. Plating Sn	7440-31-5			0.003408	1000000	327071.09375		
<b>External Plating Total:</b>						<b>0.003408</b>	<b>1000000</b>	<b>327071.09375</b>
Inter. Plating Ni	7440-02-0			0.000000	0	0		
Inter. Plating Ag	7440-22-4			0.000023	1000000	2397.26855469		
<b>Internal Plating Total:</b>						<b>0.000023</b>	<b>1000000</b>	<b>2397.26855469</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000289	750000	27734.8066406		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000096	250000	9212.94628986		
		<b>Die Attach Total:</b>				<b>0.000385</b>	<b>1000000</b>	<b>36947.7539862</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.000147	50000	14107.3242188
				Bromine (Br)	40093-93-8	0.000000	0	0
Silica (SiO2)	60676-86-0			0.002261	890000	216984.078125		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.000127	50000	12187.9609375		
Carbon Black (C)	1333-86-4			0.000005	2000	479.840942383		
<b>Encapsulation Total:</b>						<b>0.002540</b>	<b>1000000</b>	<b>243759.203125</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000070	1000000	6717.7734375		

TOTAL MASS (g): 0.010420